

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-10 (canceled).

Claim 11 (currently amended): A method for manufacturing an electronic component, comprising the steps of:

preparing a pair of substantially round conductive wires defining a pair of lead terminals;

bending one end portion of each of the pair of the conductive wires outwards at an angle of about 90 degrees;

forming a flat portion on each of the pair of substantially round conductive wires by press extending at least the portion on ~~the~~ a tip side from the bending point so as to be extended substantially parallel to a lead portion of a respective one of the pair of lead terminals, such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires;

forming a cup-shaped holder portion by bending the flat portion inwards;

holding both end portions of a piezoelectric element in a pair of the cup-shaped holder portions; and

electrically and mechanically connecting the cup-shaped holder portions and the electrodes formed in both end portions of the piezoelectric element by using a conductive joining material.

Claim 12 (currently amended): A method for manufacturing an electronic component as claimed in claim 11, further comprising the step of plating molten solder on each of the pair of conductive wires.

Claim 13 (currently amended): A method for manufacturing an electronic component as claimed in claim 11, wherein the lead portions as-at the other end of each of the pair of conductive wires are welded and fixed to a metal hoop material with pilot holds having a fixed distance therebetween.

Claim 14 (currently amended): A method for manufacturing an electronic component as claimed in claim 11, wherein the step of bending one end portion of each of the pair of conductive wires outwards at an angle of about 90 degrees is done at a location about two thirds away from the tip of the flat portions.

Claim 15 (original): A method for manufacturing an electronic component as claimed in claim 11, further comprising the step of providing a capacitor element between the cup-shaped holder portions and a tip portion of one of the lead terminals, and electrically and mechanically connecting the capacitor to the holder portions via the conductive joining material.

Claim 16 (original): A method for manufacturing an electronic component as claimed in claim 11, further comprising the step of integrally sealing the piezoelectric element, the pair of lead terminals and the conductive joining material in a packaging resin.

Claim 17 (original): A method for manufacturing an electronic component according to Claim 11, wherein the electronic component is a resonator.

Claim 18 (original): A method for manufacturing an electronic component according to Claim 11, wherein the piezoelectric element is an energy trap thickness shear vibration mode element.

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Claim 19 (original): A method for manufacturing an electronic component according to Claim 11, wherein each of the lead terminals are made of a round lead wire of about 0.48 mm in diameter.

Claim 20 (original): A method for manufacturing an electronic component according to Claim 11, wherein each of the lead terminals includes a wire made of a low-carbon steel and having copper plated on a surface thereof and a molten solder plated on the copper plating.

Claim 21 (original): A method for manufacturing an electronic component according to Claim 11, wherein a width of the flat portions is about 0.8 mm to about 1.0 mm and a thickness of the flat portions is about 0.15 mm to about 0.2 mm.